

Title (en)

Compact head for the application of hot melt adhesive

Title (de)

Kompakter Kopf zum Aufbringen von Heißklebstoff

Title (fr)

Tête compacte pour l'application de colles thermofusibles

Publication

EP 2119509 A3 20100217 (FR)

Application

EP 09159904 A 20090511

Priority

ES 200801391 A 20080514

Abstract (en)

[origin: EP2119509A2] The head has an adhesive melting reservoir (1) including, in its base, a series of passage outlets (5) communicating with a lower chamber (6), which communicates with an application head (2) i.e. nozzle, through a duct (7). The reservoir is connected to the application head, and surrounded by electrical resistors (8) housed in a peripheral chamber (4) filled with an insulating material. The reservoir is realized with a tight seal to avoid influence of external air on the adhesive, and surrounded by an insulating layer to prevent heat loss at outside.

IPC 8 full level

B05C 5/04 (2006.01); **B05C 11/10** (2006.01)

CPC (source: EP ES)

B05C 11/1042 (2013.01 - EP ES)

Citation (search report)

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Designated contracting state (EPC)

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DOCDB simple family (publication)

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